

Compound Application Procedure

Compound Description: EMI Conductivity
Applicable Technologies: SLA, SLS, FDM, Digital Printed
Revision Level: A
Revision Date: March 2007

Legend: ■ -Application Notes ● - Work Content ▲ -Inspection

- Copper Coat RP© is fast drying and easy to apply.
- Secure the following materials and supplies:
 - Copper RP©
 - Copper Powder
 - Paint brush (supplied)
 - Masking tape
- Mask off the area that requires EMI shielding with masking tape, leaving the area for application open for the materials to be applied.
- Brush 1-3 coats of the Copper RP© onto the part depending on the amount of shielding required. Allow 5 minutes to dry in between each coat.
- For a conductive surface, apply copper powder to the Copper RP© with a brush. Do not coat with anything else.
- Never wait over an hour to apply the next layer of coating. This applies to the same or other tempering coatings and materials. This may damage the previous coat breaking down the chemical materials.
- It will take 12 hours to cure, but the part can be handled and shipped within one hour.